CXA1511L/M

Preamplifier for Remote Control Signal Reception

Description

The CXA1511L/M is a bipolar IC used for preamplifiers that receive signals in infrared remote control systems. These ICs consist of a first-stage amplifier, limiter amplifier, band-pass filter, band elimination filter, signal waveform detection circuit and waveform shaping circuit.

Features

- Low power consumption (Vcc = 5V, 9mW typ.)
- Low supply voltage (Vcc = 5V)
- Filters (center frequency can be varied through external resistor: fo = 30kHz to 60kHz, 40kHz typ.)
- · Elimination of inductors prevents magnetic field inductance interference.
- · Optical reception diode can be coupled directly.
- Collector output (pull-up resistor, TTL and CMOS can be connected directly)

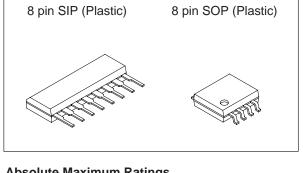
Applications

TVs, VCRs, audio equipment

Structure

Bipolar silicon monolithic IC

Block Diagram and Pin Configuration



Absolute Maximum Ratings

- Supply voltage 7 V °C • Operating temperature Topr -20 to +75
- Storage temperature Tstg -65 to +150 $^{\circ}$ C
- Allowable power dissipation

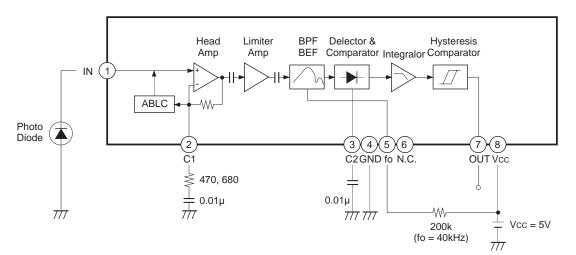
600 mW (SIP)

· Allowable power dissipation

300 mW (SOP)

Operating Conditions

 Supply voltage 4.7 to 5.3 V



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Pin Description

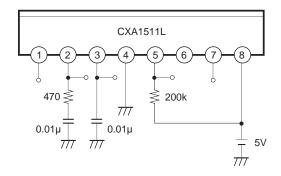
Pin voltage depends on the DC Characteristics Measurement Circuit.

| Pin No. | Symbol | Pin voltage | Equivalent circuit | Description |
|------------|--------|----------------|--|---|
| 1 | IN | 2.8V | 47k 160k | Input pin. Connect optical reception diode to GND. |
| 2 | C1 | 2.8V | Vcc 40μΑ↓ \$8k Vcc 7/7/ \$40μΑ 2 \$8k 7/7/ \$40μΑ | Connect a resistor and capacitor in series to GND, and set the frequency response and gain of "Head Amp". When the resistor is large and the capacitor small, the gain is small. When the capacitor is large, sensitivity decreases in relation to the transient response. |
| 3 | C2 | 1.9V | 330k → 30nA ↓ 30µA ↓ 30µA ↓ 30µA | Connect a detection capacitor to GND. When the capacitor is large, sensitivity decreases in relation to the mean value detection and transient response. When the capacitor is small, fluctuation of the peak detection and output pulse width increases. The capacitor in usage is 0.01µF (typ.). Set output pulse width fluctuation and noise elimination characteristics to be optimum. |
| 4 | GND | | | GND pin. Adopt a pattern design that will allow external parts to be located as closely as possible to this pin. Ground them all at the same point. The transport distance and noise elimination characteristics are greatly influenced by the pattern design surrounding the GND. |
| 5 | fo | 1.4V | 4p | Connect a resistor to the power supply. Set the center frequency of the built-in BPF. See "External resistor at Pin 5 vs. Center frequency response" on Page 6. |

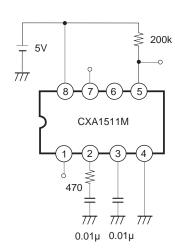
| Pin No. | Symbol | Pin voltage | Equivalent circuit | Description |
|------------|--------|---------------------------------|---|--------------------------------------|
| 6 | N.C. | | | No connected pin. Connect to GND. |
| 7 | OUT | 5.0V (High) 0.6V (Low) | 30k ₹ 7/1/ 7/1/ 7/1/ 7/1/ 7/1/ 7/1/ 7/1/ 7/ | Output pin. |
| 8 | Vcc | 5.0V | | Supply voltage pin. |

DC Characteristics Measurement Circuit

(CXA1511L)



(CXA1511M)



 $(Vcc = 5V, Ta = 25^{\circ}C)$

Electrical Characteristics

| | Measurement condition | u | Measurement | | | | <u>.</u> | Domorke |
|-----------------|-----------------------|----------------|-------------|-----------------------------|--------|--------------|--------------|--|
| Signal | Level | WS-NO | point | IVIIII. I yp. IVIAX. Offile | 구 - | <u>م</u> | <u>=</u> | אפווומואס |
| | S | S1, 3, 7 | 4 | 2.3 | 2.8 | 3.3 | > | |
| | S | S1, 2, 3, 4, 7 | 4 | 9.0 | 1.2 | 1.8 | > | 100µA is flown out from Pin 1. |
| | SS | S3, 7, 8 | ၁ | | 9.0 | 1.3 | > | |
| 40kHz CW | 30µVp-p S2 | S2, 5, 6, 9 | В | 75 | 81 | 85 | dB | |
| 30кНz, 37кНz CW | 40µVp-p | S2, 5, 6, 9 | В | 2 | 10 | | dB N | Note 1) |
| 40kHz, 48kHz CW | 40µVp-p S2, 5, 6, 9 | 2, 5, 6, 9 | В | 2 | 19 | | N Bb | Note 2) |
| 40kHz CW | 200mVp-p S1, 2, 6, 7 | 1, 2, 6, 7 | ∢ | 31 | 40 | 64 | N N n | Note 3) Input level is taken Vi and measuring value is taken Vx. |
| burst wave | 60µVp-p S2, 5, 6, 7 | 2, 5, 6, 7 | O | 440 | 2 099 | 022 | hs B | Burst wave signal with a 1.2ms, 40kHz cycle is input. |
| | S3 | S3, 7 | D | 1.0 1.8 | | 2.8 | mA | |

Note 1) The level ratio between AC level at 37kHz and that at 30kHz is taken A1 [dB].

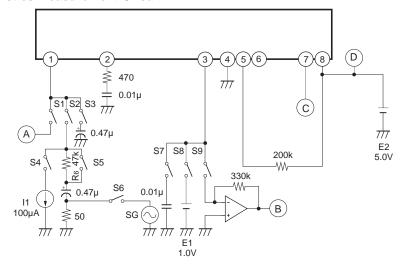
A1=20log measuring value (f = 37kHz) measuring value (f = 30kHz)

Note 2) The level ratio between AC level at 40kHz and that at 48kHz is taken A2 [dB].

A2=20log measuring value (f = 40kHz) measuring value (f = 48kHz)

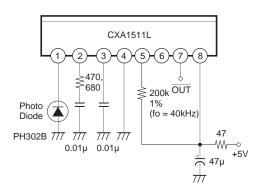
Note 3) rin= $\frac{47k\Omega}{(Vi/Vx)-1)}$ [k Ω]

Electrical Characteristics Measurement Circuit

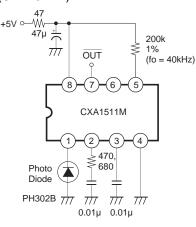


Application Circuit

(CXA1511L)





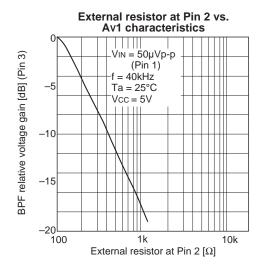


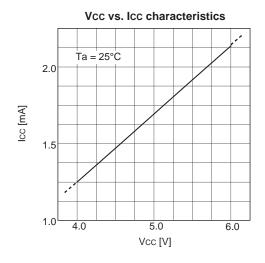
Description of Operation (See the Block Diagram.)

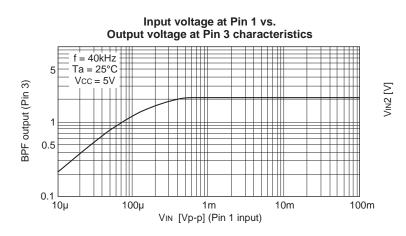
Receives infrared signals transmitted from the infrared remote control commander with a photodiode to output them as rectangular waves.

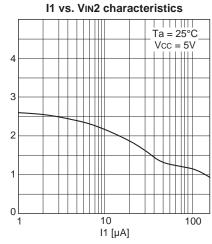
| I/O pin | Waveform | Operation |
|--------------------------------------|--|--|
| Pin 1 Input waveform | 40µVp-p to 2.5Vp-p 600µs typ. 40kHz (typ.) | Converts the signal current of a photodiode into voltage and amplifies it. |
| Pin 3 BPF output waveform | | Suppresses the noise component with BPF and BEF. |
| Hysteresis comparator input waveform | | Detects the signal component and performs wave detection. |
| Pin 7 Output waveform | 5V 0.6V (typ.) | Integrates the signal component and outputs it as rectangular wave from the hysteresis comparator. |

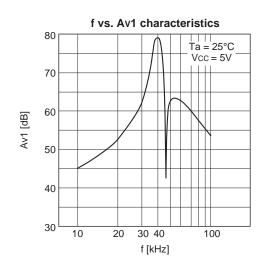
Example of Representative Characteristics

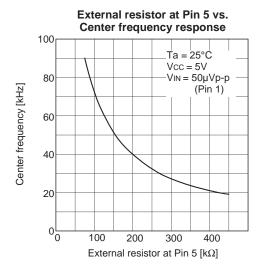








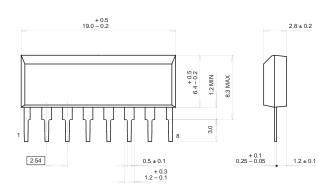




Package Outline Unit: mm

CXA1511L

8PIN SIP (PLASTIC)

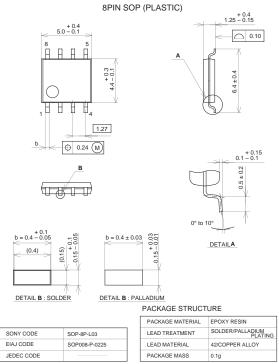


PACKAGE STRUCTURE

| SONY CODE | SIP-8P-02 |
|------------|---------------|
| EIAJ CODE | SIP008-P-0340 |
| JEDEC CODE | |

| PACKAGE MATERIAL | EPOXY RESIN |
|------------------|----------------|
| LEAD TREATMENT | SOLDER PLATING |
| LEAD MATERIAL | COPPER ALLOY |
| PACKAGE MASS | 0.7g |

CXA1511M



NOTE: PALLADIUM PLATING

This product uses S-PdPPF (Sony Spec.-Palladium Pre-Plated Lead Frame).